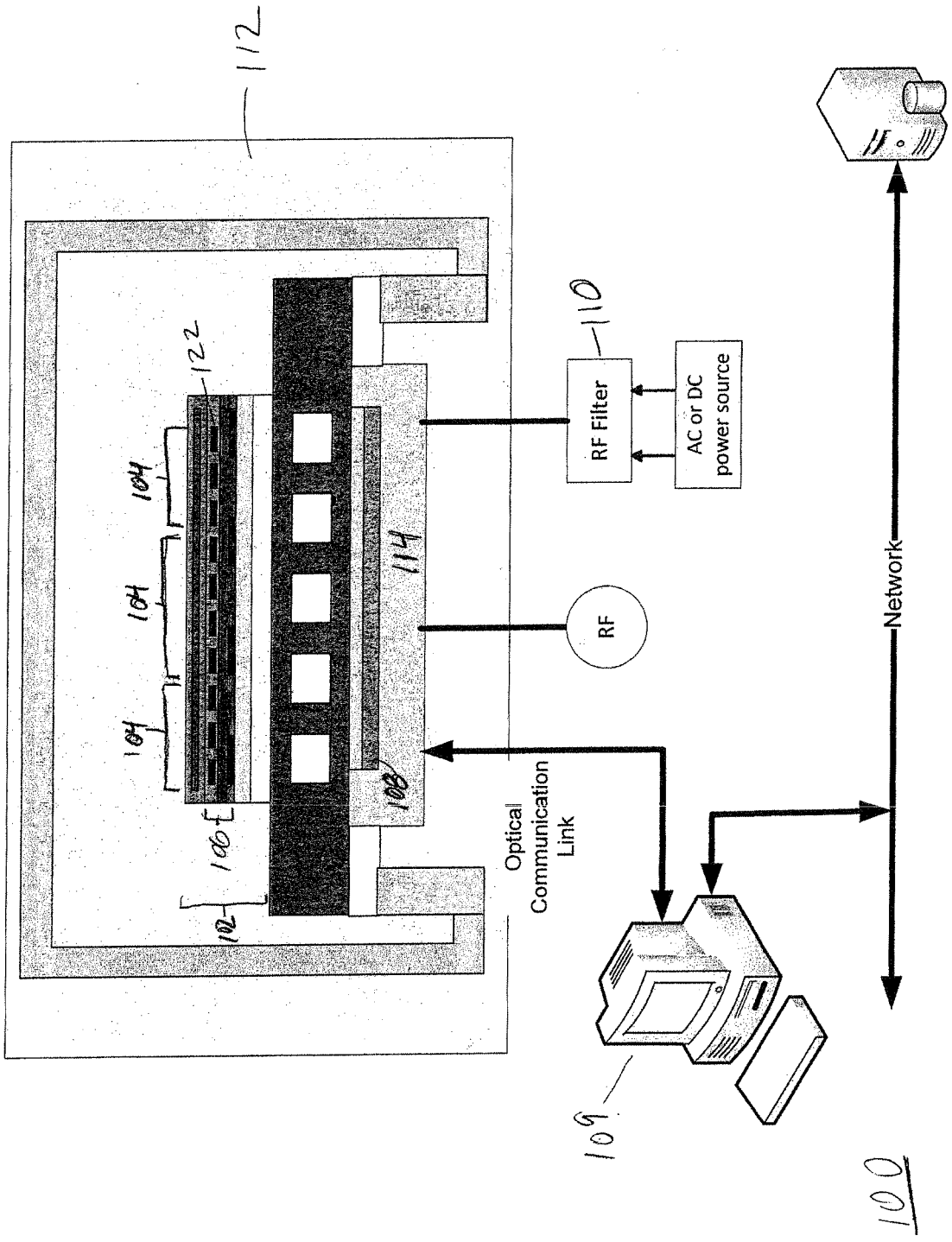
112
122
104
104
104
106
102
114
108
110
RF Filter
AC or DC power source
RF
Optical Communication Link
Network
109
100

Fig 1

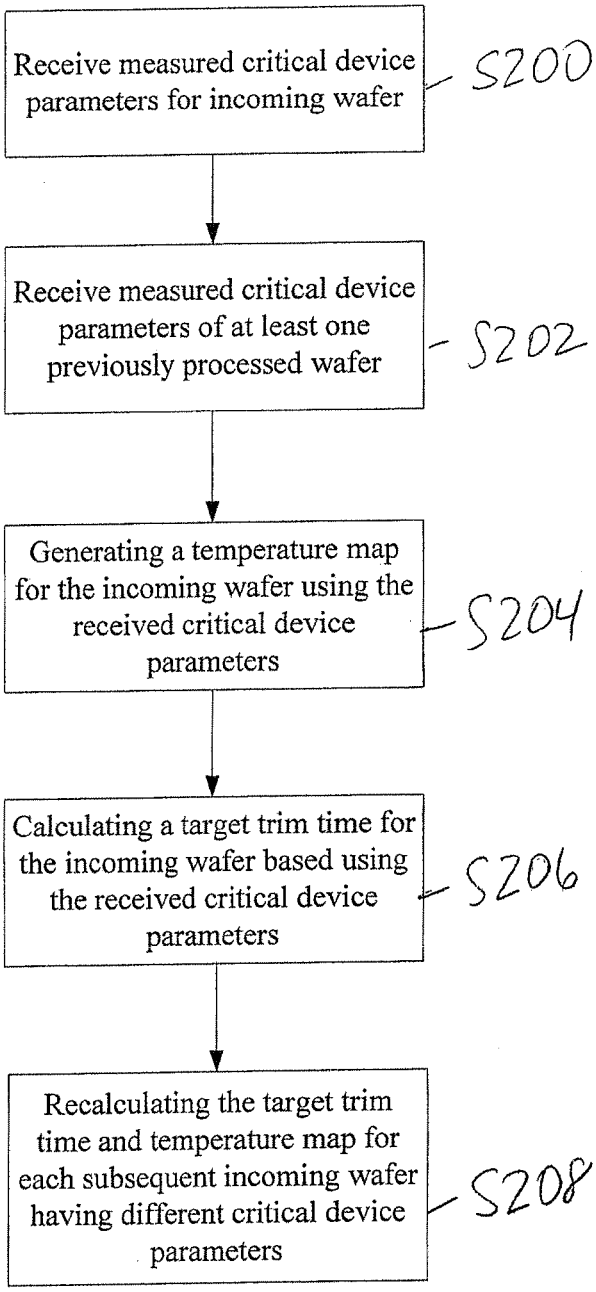
Receive measured critical device parameters for incoming wafer
S200
Receive measured critical device parameters of at least one previously processed wafer
S202
Generating a temperature map for the incoming wafer using the received critical device parameters
S204
Calculating a target trim time for the incoming wafer based using the received critical device parameters
S206
Recalculating the target trim time and temperature map for each subsequent incoming wafer having different critical device parameters
S208

Fig. 2